

ABSTRACT OF THE DISCLOSURE

A photosensitive resin composition comprising an aromatic polyimide precursor, wherein a 35 μm film made by imidating ring closure on a silicon substrate has a light transmittance at a wavelength of 365 nm of at least 1% and a residual stress of at most 25 MPa. The composition can be patterned through i-line exposure followed by development with alkaline solutions, and can be imidized into low-stress polyimide patterns. Electronic components having the polyimide patterns have high reliability.

Fig. 1A to Fig. 1E:

- 1. Semiconductor Substrate
- 2. Protective Film
- 5 3. First Conductor Layer
- 4. Interlayer Insulating Film
- 5. Photosensitive Resin Layer
- 6A. Window
- 6B. Window
- 10 6C. Window
- 7. Second Conductor Layer
- 8. Surface-Protecting Layer

A B C D E F G H I J K L M N O P Q R S T U V W X Y Z